

L Number	Hits	Search Text	DB	Time stamp
1	1124	((432/247) or (432/248) or (432/249) or (432/253)).CCLS.	USPAT	2004/01/31 10:16
2	0	("(wafer or substrate) and 1").PN.	USPAT	2004/01/31 10:16
3	196	(wafer or substrate) and (((432/247) or (432/248) or (432/249) or (432/253)).CCLS.)	USPAT	2004/01/31 10:33
4	0	(219/443c).CCLS.	USPAT	2004/01/31 10:33
5	0	(219/443).CCLS.	USPAT	2004/01/31 10:34
6	0	baking and (wafer or substrate) and emissiv\$ and (photolithographic or photoresist) and film and 219/\$.ccls.	USPAT	2004/01/31 10:35
7	56	baking and (wafer or substrate) and emissiv\$ and (photolithographic or photoresist) and film	USPAT	2004/01/31 10:44
8	9	baking and (wafer or substrate).bsum. and emissiv\$ and film and 219/\$.ccls.	USPAT	2004/01/31 10:45
9	14	baking and (wafer or substrate).bsum. and emissiv\$ and film and 118/\$.ccls.	USPAT	2004/01/31 10:48
10	9	(baking and (wafer or substrate).bsum. and emissiv\$ and film and 118/\$.ccls.) not (baking and (wafer or substrate).bsum. and emissiv\$ and film and 219/\$.ccls.)	USPAT	2004/01/31 10:45
11	126	baking and (wafer or substrate).bsum. and emissiv\$ and film	USPAT	2004/01/31 10:48
12	60	(baking and (wafer or substrate).bsum. and emissiv\$ and film) not ((baking and (wafer or substrate).bsum. and emissiv\$ and film and 118/\$.ccls.) or (baking and (wafer or substrate).bsum. and emissiv\$ and film and 219/\$.ccls.) or (baking and (wafer or substrate) and emissiv\$ and (photolithographic or photoresist) and film))	USPAT	2004/01/31 11:13
13	1010	((baking and (wafer or substrate).ab. and film) not emissiv\$) and (oven or furnace or chamber) and (baking WITH (wafer or substrate))	USPAT	2004/01/31 11:16
14	120	118/\$.ccls. and (((baking and (wafer or substrate).ab. and film) not emissiv\$) and (oven or furnace or chamber) and (baking WITH (wafer or substrate)))	USPAT	2004/01/31 11:24
15	565	uniform and (((baking and (wafer or substrate).ab. and film) not emissiv\$) and (oven or furnace or chamber) and (baking WITH (wafer or substrate)))	USPAT	2004/01/31 11:53
16	78	(uniform WITH temperature) and (((baking and (wafer or substrate).ab. and film) not emissiv\$) and (oven or furnace or chamber) and (baking WITH (wafer or substrate)))	USPAT	2004/01/31 11:25
17	487	(uniform and (((baking and (wafer or substrate).ab. and film) not emissiv\$) and (oven or furnace or chamber) and (baking WITH (wafer or substrate)))) not ((uniform WITH temperature) and (((baking and (wafer or substrate).ab. and film) not emissiv\$) and (oven or furnace or chamber) and (baking WITH (wafer or substrate))))	USPAT	2004/01/31 11:54

18	430	((uniform and (((baking and (wafer or substrate).ab. and film) not emissiv\$) and (oven or furnace or chamber) and (baking WITH (wafer or substrate)))) not ((uniform WITH temperature) and (((baking and (wafer or substrate).ab. and film) not emissiv\$) and (oven or furnace or chamber) and (baking WITH (wafer or substrate)))) not (118/\$.ccls. and (((baking and (wafer or substrate).ab. and film) not emissiv\$) and (oven or furnace or chamber) and (baking WITH (wafer or substrate))))	USPAT	2004/01/31 12:03
19	1	"20020086177"	USPAT; US-PGPUB	2004/01/31 12:04
20	4536	((coating or film) WITH (cover or wall\$ or interior or inner)) and (furnace or oven) and (wafer or substrate).ab.	USPAT; US-PGPUB	2004/01/31 12:06
21	402	baking.ab. and (furnace or oven) and (wafer or substrate)	USPAT	2004/01/31 12:07
22	334	(coating or film) and (baking.ab. and (furnace or oven) and (wafer or substrate))	USPAT	2004/01/31 12:09
23	97	semiconductor and ((coating or film) and (baking.ab. and (furnace or oven) and (wafer or substrate)))	USPAT	2004/01/31 12:26
24	1	(wafer or substrate) and wilson-gregory\$.xp. and emissiv\$ and black	USPAT	2004/01/31 12:29
25	0	(wafer or substrate) and wilson-gregory-a.xp. and emissiv\$	USPAT	2004/01/31 12:30
26	2	(wafer or substrate) and wilson-gregory\$.xa. and emissiv\$	USPAT	2004/01/31 12:31
27	134	(wafer or substrate) and wilson.xa. and absorb\$	USPAT	2004/01/31 12:35
28	288	(wafer or substrate) and wilson.xp. and absorb\$	USPAT	2004/01/31 12:35
29	62	semiconductor and ((wafer or substrate) and wilson.xp. and absorb\$)	USPAT	2004/01/31 12:35